

Product Change Notification

Current Date: 28-May-2025

PCN Date: 14-MAY-25

TE Connectivity

Product Change Notification: P-25-028147

Customer: Newark Electronics (167839)

Location: Chicago

Agreement: Agreement Unknown

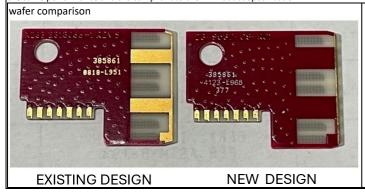
TE would like to inform you of the following change(s) to the listed TE Connectivity Product. In case of any further questions about this change(s), please contact your TE Connectivity Sales Engineer. Affected part, drawing and/or specification numbers are listed on the attached sheet(s).

General Product Description:

Multigig RT2, RT2-R, RT3 Daughtercard connectors with Differential wafers

Description of Changes

Current Differential Signal wafers have Gold plated ground pads strategically located on non-contact areas of the backside of the wafer. These pads are used for Impedance tuning of the Differential signal pairs on the opposite mating side of the wafer. The Gold and Nickel underplate over the Copper Ground pads will be replaced by extending the existing soldermask material to cover the non-contact areas. See attached photo. Samples have been tested both electrically and mechanically to verify they continue to meet the same performance and are compliant to the TE Product Specification.



Reason for Changes:			
<u> </u>	ntinued quality improvement, performance, and sustainability objectives.		
Estimated Dates:	Tanaca quality improvement, performance, and sustainability objectives.		
Last Order Date (Obsolete Parts Only):	First Date To Ship (Changed Parts Only):		
	17-NOV-2025		
Last Ship Date (Obsolete Parts Only):	Last Date for Mixed Shipments: (Changed Parts Only):		
	13-FEB-2026		

Part Number(s) being Modified:

Part Number	Part Discontinued	Customer	Customer Part	Alias Part	Substitute Part	Substitute Alias Part	Description Of
	per PCN	Drawing	Number	Number(s)	Number	Number(s)	Difference
<u>2302785-1</u>	NO						